

MECHANICAL CASE OUTLINE

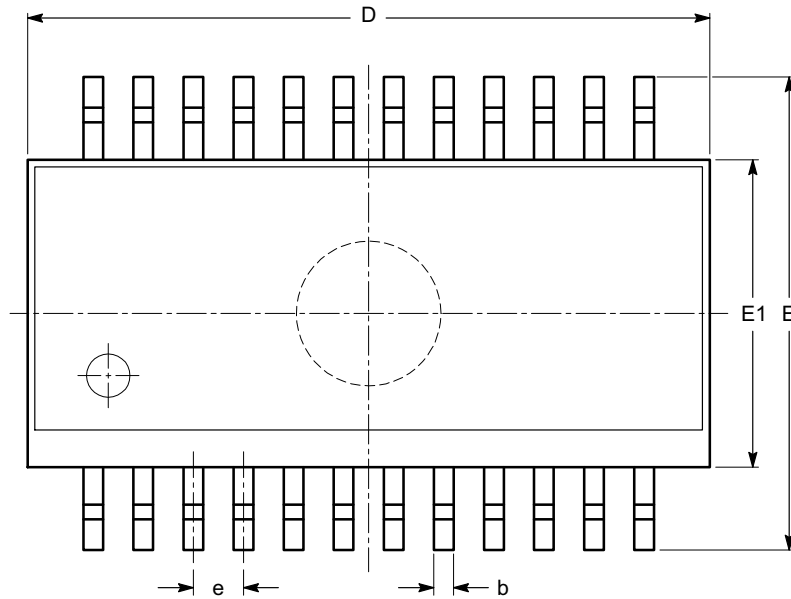
PACKAGE DIMENSIONS

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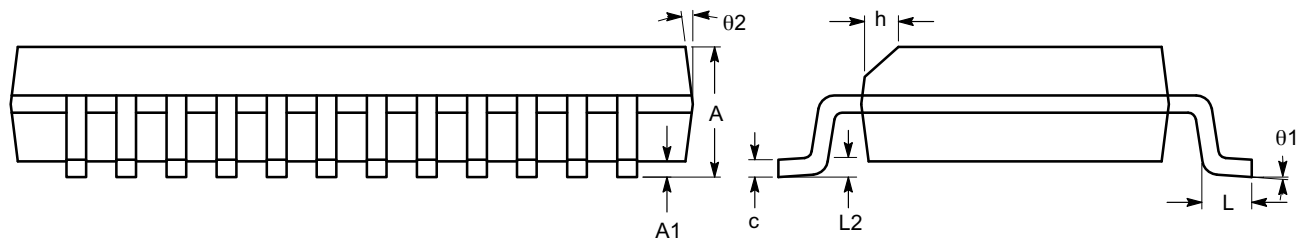
QSOP-24, 150 mils
CASE 492AB-01
ISSUE O

DATE 19 DEC 2008



SYMBOL	MIN	NOM	MAX
A	1.37		1.73
A1	0.10		0.25
b	0.20		0.30
c	0.19		0.25
D	8.56		8.74
E	5.82		6.19
E1	3.81		3.98
e	0.635 BSC		
h	0.28		0.48
L	0.41		0.86
L2	0.254 BSC		
θ1	0°		8°
θ2	7° BSC		

TOP VIEW



SIDE VIEW

END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-137.

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